

ABSTRACT

A multilayer circuit board and a manufacturing method for producing the board via simple manufacturing processes employing a droplet jetting method, where the

5 inter-layer insulating film can be easily made flat. The multilayer circuit board includes at least two wiring layers, an inter-layer insulating film provided between every adjacent two of the wiring layers, and conductive posts for providing electrical conductivity between the wiring layers. The manufacturing method includes the step of forming the inter-layer insulating film by changing the film thickness of the

10 inter-layer insulating film according to a concavo-convex shape of an area where the inter-layer insulating film is formed, so as to level an upper surface of the inter-layer insulating film. The concavo-convex shape may be computed based on design data of a circuit pattern for forming the wiring layers and the conductive posts, or may be measured before the inter-layer insulating film is formed.